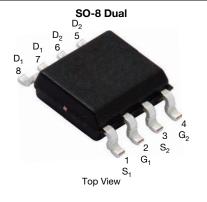


# Dual N-Channel 60 V (D-S) 175 °C MOSFET

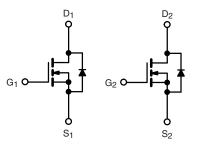
| PRODUCT SUMMARY                           |       |  |  |  |
|---|-------|--|--|--|
| V <sub>DS</sub> (V)                       | 60    |  |  |  |
| $R_{DS(on)} (\Omega)$ at $V_{GS} = 10 V$  | 0.028 |  |  |  |
| $R_{DS(on)} (\Omega)$ at $V_{GS} = 4.5 V$ | 0.030 |  |  |  |
| I <sub>D</sub> (A) per leg                | 7     |  |  |  |
| Configuration                             | Dual  |  |  |  |



#### FEATURES

- TrenchFET<sup>®</sup> power MOSFET
- 100 %  $\rm R_g$  and UIS tested





N-Channel MOSFET N-C

N-Channel MOSFET

| <b>ABSOLUTE MAXIMUM RATINGS</b> ( $T_C = 25 \text{ °C}$ , unless otherwise noted) |                         |                                   |             |      |  |
|---|-------------------------|-----------------------------------|-------------|------|--|
| PARAMETER   |                         | SYMBOL                            | LIMIT       | UNIT |  |
| Drain-Source Voltage  |                         | V <sub>DS</sub>                   | 60          | V    |  |
| Gate-Source Voltage   |                         | V <sub>GS</sub>                   | ± 20        | V    |  |
| Continuous Drain Current  | T <sub>C</sub> = 25 °C  | 1                                 | 7           |      |  |
|   | T <sub>C</sub> = 125 °C | I <sub>D</sub>                    | 4           |      |  |
| Continuous Source Current (Diode Conduction) a                                    |                         | ا <sub>S</sub>                    | 3.6         | A    |  |
| Pulsed Drain Current <sup>b</sup>   |                         | I <sub>DM</sub>                   | 28          |      |  |
| Single Pulse Avalanche Current  | L = 0.1 mH              | I <sub>AS</sub>                   | 18          |      |  |
| Single Pulse Avalanche Energy   |                         | E <sub>AS</sub>                   | 16.2        | mJ   |  |
| Maximum Power Dissipation <sup>b</sup>  | T <sub>C</sub> = 25 °C  | PD                                | 4           | W    |  |
|   | T <sub>C</sub> = 125 °C | гD                                | 1.3         | vV   |  |
| Operating Junction and Storage Temperature  | Range                   | T <sub>J</sub> , T <sub>stg</sub> | -55 to +175 | °C   |  |

| THERMAL RESISTANCE RATINGS |                        |                   |       |      |  |  |
|----------------------------|------------------------|-------------------|-------|------|--|--|
| PARAMETER                  |                        | SYMBOL            | LIMIT | UNIT |  |  |
| Junction-to-Ambient        | PCB Mount <sup>c</sup> | R <sub>thJA</sub> | 110   | °C/W |  |  |
| Junction-to-Foot (Drain)   |                        | R <sub>thJF</sub> | 34    | 0/10 |  |  |

#### Notes

a. Package limited.

b. Pulse test; pulse width  $\leq$  300 µs, duty cycle  $\leq$  2 %.

c. When mounted on 1" square PCB (FR4 material).

## P2806HV

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| <b>SPECIFICATIONS</b> ( $T_c = 25$ °C, unless otherwise noted) |                     |   |   |      |       |       |      |  |
|--|---------------------|---|---|------|-------|-------|------|--|
| PARAMETER  | SYMBOL              | TEST CONDITIONS   |   | MIN. | TYP.  | MAX.  | UNIT |  |
| Static   |                     |   |   |      |       |       |      |  |
| Drain-Source Breakdown Voltage                                 | V <sub>DS</sub>     | $V_{GS} = 0 V, I_D = 250 \mu A$   |   | 60   | -     | -     | v    |  |
| Gate-Source Threshold Voltage                                  | V <sub>GS(th)</sub> | V <sub>DS</sub> =   | $V_{DS} = V_{GS}$ , $I_D = 250 \ \mu A$                       |      | 2.0   | 2.5   | v    |  |
| Gate-Source Leakage  | I <sub>GSS</sub>    | V <sub>DS</sub> =   | 0 V, V <sub>GS</sub> = ± 20 V                                 | -    | -     | ± 100 | nA   |  |
|  |                     | $V_{GS} = 0 V$  | V <sub>DS</sub> = 60 V  | -    | -     | 1     |      |  |
| Zero Gate Voltage Drain Current                                | I <sub>DSS</sub>    | $V_{GS} = 0 V$  | $V_{DS} = 60 \text{ V}, \text{ T}_{J} = 125 ^{\circ}\text{C}$ | -    | -     | 50    | μA   |  |
|  |                     | $V_{GS} = 0 V$  | V <sub>DS</sub> = 60 V, T <sub>J</sub> = 175 °C               | -    | -     | 150   |      |  |
| On-State Drain Current <sup>a</sup>                            | I <sub>D(on)</sub>  | $V_{GS} = 10 \text{ V}$   | $V_{DS} \ge 5 V$  | 20   | -     | -     | Α    |  |
|  |                     | $V_{GS} = 10 \text{ V}$   | I <sub>D</sub> = 4.5 A-                                       |      | 0.028 | -     | Ω    |  |
| Drain-Source On-State Resistance <sup>a</sup>                  | R <sub>DS(on)</sub> | $V_{GS} = 10 V$   | I <sub>D</sub> = 4.5 A, T <sub>J</sub> = 125 °C               | -    | 0.066 | -     |      |  |
|  | D0(01)              | $V_{GS} = 10 V$   | I <sub>D</sub> = 4.5 A, T <sub>J</sub> = 175 °C               | -    | 0.081 | -     |      |  |
|  |                     | $V_{GS} = 4.5 V$  | I <sub>D</sub> = 4 A-   |      | 0.030 | -     |      |  |
| Forward Transconductance <sup>f</sup>                          |                     | V <sub>DS</sub>   | = 15 V, I <sub>D</sub> = 4.5 A                                | -    | 15    | -     | S    |  |
| Dynamic <sup>b</sup>   |                     |   |   |      |       |       |      |  |
| Input Capacitance  | C <sub>iss</sub>    |   | V <sub>GS</sub> = 0 V V <sub>DS</sub> = 25 V, f = 1 MHz       | -    | 600   | 750   | pF   |  |
| Output Capacitance   | Coss                | $V_{GS} = 0 V$  |   | -    | 110   | 140   |      |  |
| Reverse Transfer Capacitance                                   | C <sub>rss</sub>    |   |   | -    | 50    | 62    |      |  |
| Total Gate Charge <sup>c</sup>                                 | Qg                  |   |   | -    | 11.7  | 18    |      |  |
| Gate-Source Charge <sup>c</sup>                                | Q <sub>gs</sub>     | $V_{GS} = 10 \text{ V}$   | V V <sub>DS</sub> = 30 V, I <sub>D</sub> = 5.3 A              | -    | 1.8   | 2.7   | nC   |  |
| Gate-Drain Charge <sup>c</sup>                                 | Q <sub>gd</sub>     |   |   | -    | 2.8   | 4.2   |      |  |
| Gate Resistance  | Rg                  | f = 1 MHz   |   | 1.3  | -     | 6     | Ω    |  |
| Turn-On Delay Time <sup>c</sup>                                | t <sub>d(on)</sub>  | $V_{DD} = 30 \text{ V}, \text{ R}_L = 6.8 \ \Omega$ $\text{I}_D \cong 4.4 \text{ A}, \text{ V}_{\text{GEN}} = 10 \text{ V}, \text{ R}_g = 1 \ \Omega$ |   | -    | 7     | 11    |      |  |
| Rise Time <sup>c</sup>   | t <sub>r</sub>      |   |   | -    | 3.3   | 5     | - ns |  |
| Turn-Off Delay Time <sup>c</sup>                               | t <sub>d(off)</sub> |   |   | -    | 22.4  | 33.5  |      |  |
| Fall Time <sup>c</sup>   | t <sub>f</sub>      |   |   | -    | 2.1   | 3.2   |      |  |
| Source-Drain Diode Ratings and Characteristics <sup>b</sup>    |                     |   |   |      |       |       |      |  |
| Pulsed Current <sup>a</sup>                                    | I <sub>SM</sub>     |   |   | -    | -     | 28    | Α    |  |
| Forward Voltage  | V <sub>SD</sub>     | I <sub>F</sub> = 2 A, V <sub>GS</sub> = 0 V   |   | -    | 0.75  | 1.1   | V    |  |

Notes

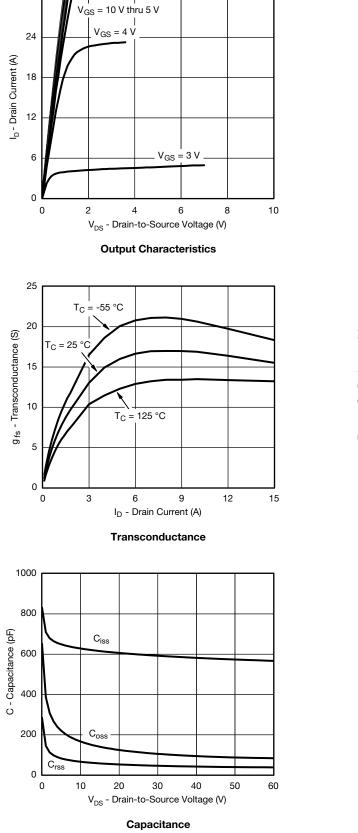
a. Pulse test; pulse width  $\leq$  300 µs, duty cycle  $\leq$  2 %. b. Guaranteed by design, not subject to production testing.

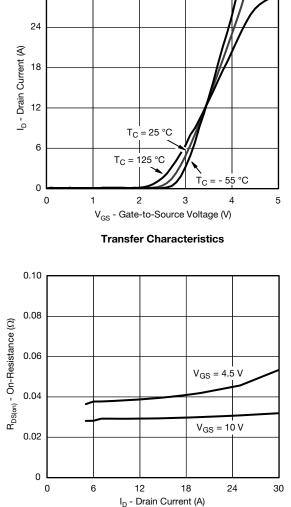
c. Independent of operating temperature.

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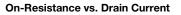


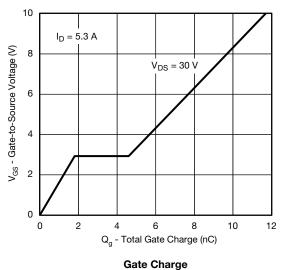
## **TYPICAL CHARACTERISTICS** (T<sub>A</sub> = 25 °C, unless otherwise noted)



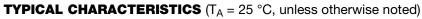


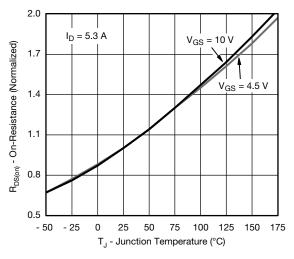
30



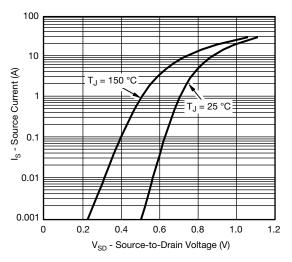




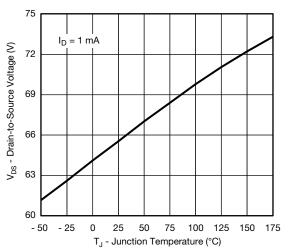




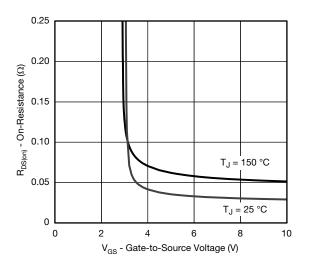
**On-Resistance vs. Junction Temperature** 



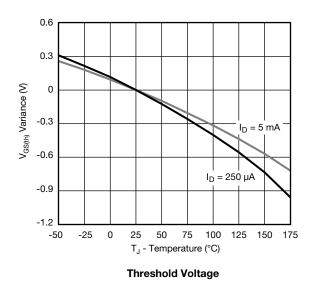
Source Drain Diode Forward Voltage



Drain Source Breakdown vs. Junction Temperature



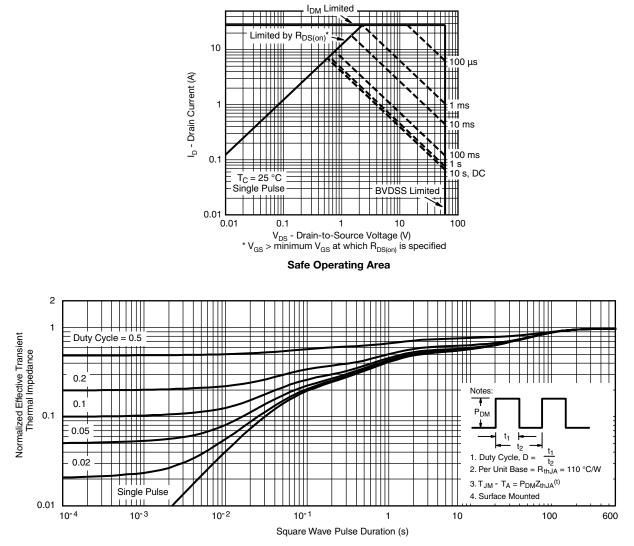
On-Resistance vs. Gate-to-Source Voltage



服务热线:400-655-8788



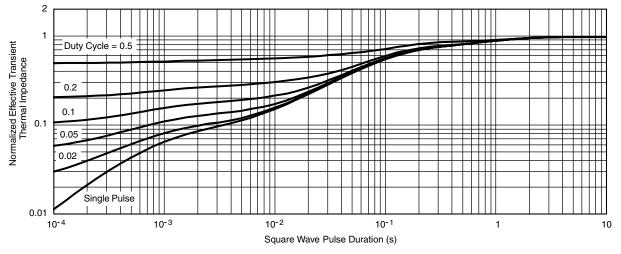
### **THERMAL RATINGS** ( $T_A = 25 \text{ °C}$ , unless otherwise noted)



Normalized Thermal Transient Impedance, Junction-to-Ambient



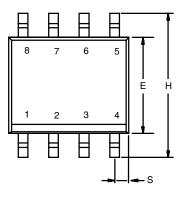
## **THERMAL RATINGS** ( $T_A = 25$ °C, unless otherwise noted)

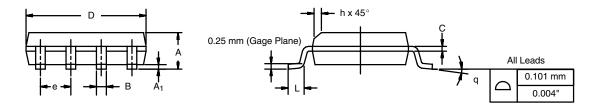


Normalized Thermal Transient Impedance, Junction-to-Foot



# SOIC (NARROW): 8-LEAD JEDEC Part Number: MS-012

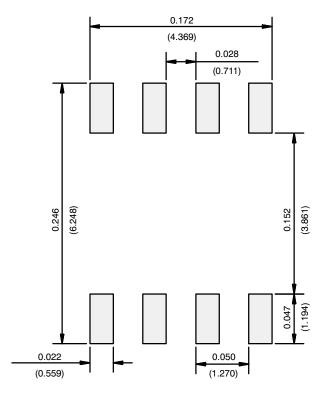




|   | MILLIM | IETERS | INCHES    |       |  |
|---|--------|--------|-----------|-------|--|
| DIM   | Min    | Мах    | Min       | Max   |  |
| A   | 1.35   | 1.75   | 0.053     | 0.069 |  |
| A <sub>1</sub>                              | 0.10   | 0.20   | 0.004     | 0.008 |  |
| В   | 0.35   | 0.51   | 0.014     | 0.020 |  |
| С   | 0.19   | 0.25   | 0.0075    | 0.010 |  |
| D   | 4.80   | 5.00   | 0.189     | 0.196 |  |
| E   | 3.80   | 4.00   | 0.150     | 0.157 |  |
| е   | 1.27   | BSC    | 0.050 BSC |       |  |
| Н   | 5.80   | 6.20   | 0.228     | 0.244 |  |
| h   | 0.25   | 0.50   | 0.010     | 0.020 |  |
| L   | 0.50   | 0.93   | 0.020     | 0.037 |  |
| q   | 0°     | 8°     | 0°        | 8°    |  |
| S   | 0.44   | 0.64   | 0.018     | 0.026 |  |
| ECN: C-06527-Rev. I, 11-Sep-06<br>DWG: 5498 |        |        |           |       |  |



### **RECOMMENDED MINIMUM PADS FOR SO-8**



Recommended Minimum Pads Dimensions in Inches/(mm)



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